

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-3 (cancelled)

Claim 4 (currently amended): A connector chip comprising:

a rectangular parallelepiped insulating substrate having six surfaces, and
a plurality of conductive paths formed on an outer peripheral surface, which is constituted by four continuous surfaces of the six surfaces, at a predetermined interval in an opposing direction of reaming two opposing surfaces of the six surfaces, and running round on the outer peripheral surface,

wherein on at least a pair of the surfaces opposing to each other among the four surfaces, insulating layers having a property of repelling molten solder are formed respectively between portions of two adjoining conductive paths among the plurality conductive paths, located on the pair of the surfaces, and the insulating layers are formed of an epoxy resin, a glass or the like.

Claim 5 (original): The connector chip according to claim 4, wherein each of the conductive paths is constituted by forming one or more plated layers over a base layer made of a metal thick film or a metal thin film.

Claim 6 (cancelled)

Claim 7 (previously presented): The connector chip according to claim 4, wherein the insulating layers formed on one surface of the pair of the surfaces and the insulating layers formed on the other surface of the pair of the surfaces have different colors.

Claim 8 (original): The connector chip according to claim 4, wherein in the insulating substrate, a plurality of conductive-path-formed portions where the conductive paths are formed and a plurality of conductive-path-unformed portions where the conductive paths are not formed are alternately arranged along a center line so that the conductive-path-formed portions and the conductive-path-unformed portions share the center line; and

a width of each of the conductive-path-formed portions orthogonal to the center line is smaller than a width of each of the conductive-path-unformed portions orthogonal to the center line.

Claim 9 (original): The connector chip according to claim 4, wherein in the insulating substrate, a plurality of conductive-path-formed portions where the conductive paths are formed and a plurality of conductive-path-unformed portions where the conductive paths are not formed are alternately arranged along a center line so that the conductive-path-formed portions and the conductive-path-unformed portions share the center line; and

a width of each of the conductive-path-formed portions orthogonal to the center line is larger than a width of each of the conductive-path-unformed portions orthogonal to the center line.

Claim 10 (original): The connector chip according to claim 5, wherein the base layer is formed of a metal thick film including Ag (silver) or a metal thin film of a Ni--Cr (nickel-chromium) alloy or Cu (copper); and

each of the one or more plated layers comprises a first plated layer made of Cu (copper) or Ni (nickel) and a second plated layer made of a Sn (tin) alloy or Sn (tin), formed over the first plated layer.

Claims 11-12 (cancelled)